

Application No. 10/534,190  
Response to Office Action dated July 31, 2007  
Paper dated October 31, 2007  
Attorney Docket No. 1217-051112

**Amendments to the Specification**

Please amend the paragraph bridging pages 16-17 of the specification as follows:

In the film carrier tape for mounting electronic parts of the present invention, the film carrier formed by splitting and/or dividing the solder resist layer is not limited to the aforesaid CSP or BGA, and the film carrier can be applied to general TAB tapes. For example, as shown in Figs. 5(a) and 5(b), the film carrier can be applied to a film carrier tape for mounting electronic parts wherein a solder resist layer is formed in a region of not less than 30% 20% of the wiring patterns (except terminal portions). In Fig. 5(a), an example wherein a solder resist layer having been divided into 12 sections is formed on wiring patterns 15 formed on a surface of an insulating film 11 having a device hole is shown. The wiring patterns shown in Fig. 5(a) are only examples and do not restrict those employable in the present invention. In Fig. 5(b), an example wherein the solder resist layer 20 is divided into 2 sections is shown, but in this figure, wiring patterns formed on a surface of the insulating film 11 are not shown. Dividing of the solder resist layer is useful for a film carrier tape for mounting electronic parts wherein a solder resist layer is formed in a region of not less than 30% 20% of wiring patterns except terminal portions, as shown in Figs. 5(a) and 5(b). --

**Amendments to the Abstract**

Please replace the abstract on page 30 with the following rewritten abstract:

-- A film carrier tape for mounting an electronic part includes a film carrier tape comprising including an elongated insulating film having a plurality of wiring patterns formed on a surface of the insulating film, the wiring patterns being made of a conductive metal, wherein the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each surface of the wiring patterns is divided into plural sections. Warpage distortion that heretofore occurs on each of carriers arranged, such as CSP, COF and BGA, provided in a film carrier tape for mounting an electronic part in the width direction of the tape can be reduced. --